

APPROVAL SHEET

MULTILAYER CERAMIC DIPLEXER

RFDIP Series – 1608(0603)- RoHS Compliance

Halogens Free Product

GPS 1.575 GHz/ISM 2.4 GHz Band Application

P/N: RFDIP1608060T1T

*Contents in this sheet are subject to change without prior notice.

FEATURES

- 1. Miniature footprint: 1.6 X 0.8X 0.6 mm³
- 2. Low Insertion Loss
- 3. High attenuation on 2nd harmonic suppressed
- 4. LTCC process

APPLICATIONS

1. GPS 1.575GHz/ ISM 2.4GHz band RF application

CONSTRUCTION

Figure	PIN	Connection
P3 P4	1	GND
	2	1.5GHz port
	3	Common port
P2 P1	4	2.4GHz port

DIMENSIONS

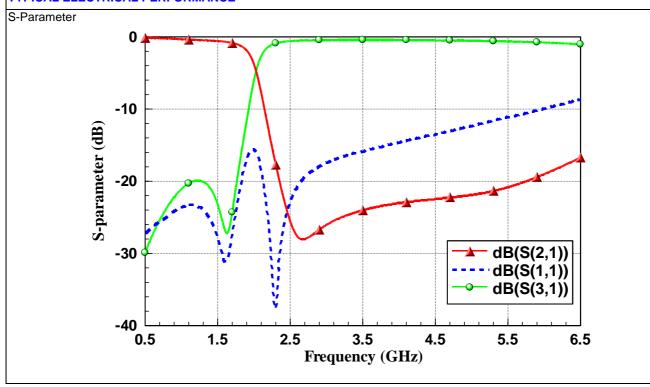
Figure	Symbol	Dimension (mm)
	L	1.60 ± 0.15
	W	0.80 ± 0.15
	Т	0.60 ± 0.10
	А	0.65 ± 0.15
	В	0.30 ± 0.15
	С	0.20 ± 0.15
	D	0.20 ± 0.15
	Е	0.25 ± 0.15
	F	0.30 ± 0.15



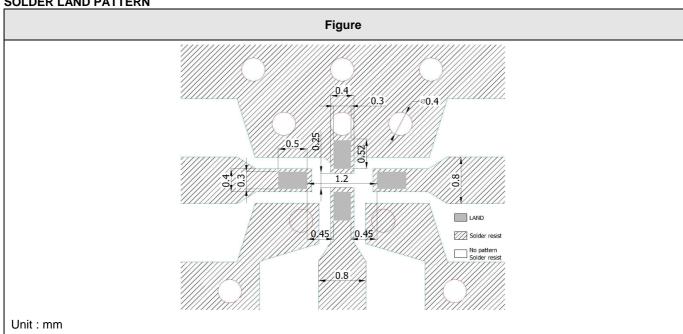
ELECTRICAL CHARACTERISTICS

Item	Specification		
Frequency range	1574-1577 MHz	2400-2500 MHz	
VSWR	2.0 max	2.0 max	
Insertion Loss	0.65 dB max.	0.8 dB max	
Attenuation (dB min.)	20 dB @2.4~2.5GHz	20 dB @1.574~1.577GHz	
Operation Temperature Range	-40°C ~ +85°C	-40°C ~ +85°C	

TYPICAL ELECTRICAL PERFORMANCE



SOLDER LAND PATTERN



through holes is 0.3 mm

Line width to de designed to match 50 $\,\Omega$ characteristic impedance, depending on PCB material and thickness. Grounding



RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature: 120~150°C, 1 minute. *Solder temperature: 270±5°C *Immersion time: 10±1 sec *Solder: Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

Approvai silect		
Temperature cycle JIS C 0025	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test.
Vibration JIS C 0040	*Frequency: 10Hz~55Hz~10Hz(1min) *Total amplitude: 1.5mm *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage. Samples shall satisfy electrical specification after test.
High temperature JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

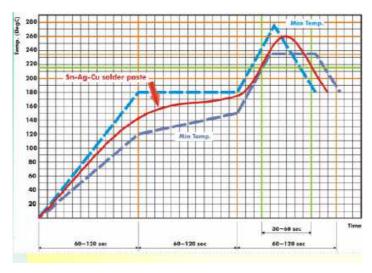


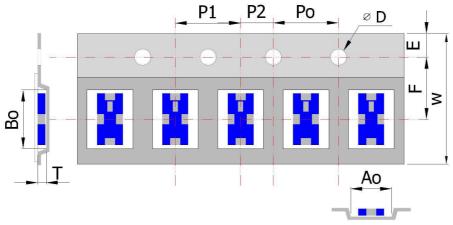
Fig 2. Infrared soldering profile

ORDERING CODE

RF	DIP	160806	0	Т	1	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RF device	DIP: Diplexer	Per 2 digits of	dimension	T: GPS/ ISM 2.4GHz	Design code	T : Reeled
		Length, Width,	0 : 0.1 mm			
		Thickness:	1 : 1.0 mm			
		e.g. :				
		1608 =				
		Length 16,				
		Width 08,				
		Thickness 06				

Minimum Ordering Quantity: 4000 pcs per reel.

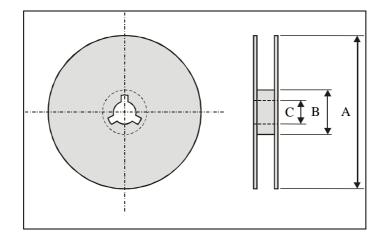
PACKAGING



Paper Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	0.975± 0.05	1.76 ±0.05	1.55 + 0.05	0.75± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	Α	В	С	
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0	

Taping Quantity:4000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity: 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.